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JFW

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Appl. No.	10/813,407	Confirmation No.	5642
First Inventor	Jiping Li	Filing Date	March 29, 2004
Tech. Center/ Art Unit	2822	Examiner	Trinh, Michael Manh
Title:	High Throughput Measurement Of Via Defects In Interconnects		
Docket No.:	008546USA	Customer No.:	34036

Santa Clara, California  
December 20, 2005

Mail Stop ISSUE FEE  
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AMENDMENT AFTER NOTICE OF ALLOWANCE

UNDER 37 C.F.R. 1.312

Dear Sir:

In response to Notice of Allowance dated April 27, 2005, please amend the above-identified application as follows.

**Amendments to the Specification** begin on page 2 of this paper.

**Amendments to the Drawings** begin on page 3 of this paper and include two replacement sheets.

**Remarks/Arguments** begin on page 4 of this paper.

An **Appendix** including two replacement drawing figures (and a cover sheet) is attached following page 4 of this paper.

OK. to  
Enter 312  
to Specification  
and Drawing  
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